Ultrasonic Heavy Wire Bonder M17

F & K DELVOTEC – The Heavy Wire Bonder specialist – delivers the perfect solution for any bonding challenge in the IGBT, smart power module and hybrid assemblies industries.

The innovative platform strategy, whereby the differing wirebond technologies and transducer frequencies can be deployed on the same machine base is continued on the F & K Model 2017. The number of different sized work areas ensure the highest flexibility in the packaging technology of the complete package spectrum.

**Advantages**
- Integrated heavy wire and heavy ribbon in one machine platform using fast system change-over
- Ensures repeatable bond quality through patented BPC for real-time adjustment of the bond parameters with varying material surfaces
- Ensures process transparency through seamless integration in industry 4.0/IOT procedures
- Offers process stability through a large choice of ultrasonic frequencies for optimum material matching
- Integrated process technology and automation from a single source
MADE FOR YOU – YOUR ADVANTAGES AT A GLANCE

- Smallest footprint on the market with maximum productivity
- Optimised scaling of your investment
- Sustainable technology through proven, exchangeable bond head principle
- Manual or automatic parts handling

- Smallest footprint on the market with double the output
- Perfect for high-volume production
- Best TCO through combination of fine wire and heavy wirebond technologies
- Pin or belt indexer with in-line pulltester

- Flexible parts handling height, up to 500 mm
- Highest flexibility with the combination of manual and automatic parts handling:
  - Two manual work holders
  - Single track indexer with manual work holder
  - Dual track indexer with bond-off station

- Largest work area on the market
- No interference from mainframe components as with gantries
- Flexible parts handling height, up to 500 mm
- Perfect for BMS and battery connections

HEAVY WIRE MACHINE MODELS

<table>
<thead>
<tr>
<th>M17</th>
<th>S</th>
<th>D</th>
<th>L</th>
<th>XL</th>
</tr>
</thead>
<tbody>
<tr>
<td>X-axis</td>
<td>254 mm (10&quot;)</td>
<td>254 mm (10&quot;)</td>
<td>652 mm (25&quot;)</td>
<td>1,133 mm (44.61&quot;)</td>
</tr>
<tr>
<td>Y-axis</td>
<td>152.4 mm (6&quot;)</td>
<td>152.4 mm (6&quot;)</td>
<td>350 mm (14&quot;)</td>
<td>702 mm (27.64&quot;)</td>
</tr>
<tr>
<td>Z-axis</td>
<td>40 mm (1.57&quot;), optional 60 mm (2.36&quot;)</td>
<td>40 mm (1.57&quot;), optional 60 mm (2.36&quot;)</td>
<td>100 mm (4&quot;)</td>
<td>40 mm (1.57&quot;)</td>
</tr>
<tr>
<td>Width</td>
<td>553 mm</td>
<td>1,073 mm</td>
<td>1,073 mm</td>
<td>1,545 mm</td>
</tr>
<tr>
<td>Height with/without signal lamp</td>
<td>2,249 / 1,721 mm</td>
<td>2,283 / 1,734 mm</td>
<td>2,503 / 1,954 mm</td>
<td>1,850 mm / -</td>
</tr>
<tr>
<td>Depth</td>
<td>1,135 mm</td>
<td>1,135 mm</td>
<td>1,237 mm</td>
<td>1,606 mm</td>
</tr>
<tr>
<td>Weight</td>
<td>780 kg</td>
<td>1,165 kg</td>
<td>1,100 kg</td>
<td>1,400 kg</td>
</tr>
</tbody>
</table>

Working height | SMEMA compliant 850-1,050 mm
Power supply | 120 V +/- 10 %, 230 V +/- 10 %, single phase, 50-60 Hz
Power | 0.5 kW
Compressed air | 4-8 bar
Vacuum connection | < -0.8 bar

The technical information provided reflects our current knowledge. The details shown do not take any particular considerations of unique cases into account.
HEAVY WIRE AND HEAVY RIBBON BOND HEAD

- **Wire diameter**
  - Standard 100-600 µm (4-24 mil)
  - Ribbon 2,000 µm x 300 µm (80 mil x 12 mil); optionally laserbonding for conductors of larger cross sections

- **Wire material**
  - Al, Cu, AlCu

- **Wire spool**
  - Spool diameter 3”, 3.5”, 4”
  - Automatic wire feed
  - Wire end recognition using CCD sensor
  - 90° wire feed angle

- **Cutting process**
  - Active, cut depth for front and back cut

- **Bond tool**
  - F & K standard 2”, optionally 2.8”, 4”
  - Development of customer specific wedges by F & K possible

- **Transducer frequencies**
  - 40, 60, 90, 120 kHz standard
  - Development of customer specific transducers by the F & K laboratory possible

- **Ultrasonic generator**
  - F & K, digital 30-250 kHz
  - Resolution < 1 Hz
  - Power max. 100 W, programmable

- **Bond force**
  - Up to 5,000 cN

- **In-head pulltest**
  - NEW High-speed in-head pulltester, programmable for each bond, up to 40 % speed improvement compared to conventional in-head pulltests

- **Consumables**
  - Patented F & K clip-on system for optimum wire feed and control
  - NEW Cutter with hardened surface for extra-long life

- **Speed**
  - 2.5 wires per second, application dependent

- **Bond head fast-change system**
  - Proven, fast-change system with intelligent bond head recognition, enables exchange of bond heads in less than 15 minutes

HEAVY WIRE MACHINE MODELS

- **M17 S**
- **M17 D**
- **M17 L**
- **M17 XL**
### MACHINE SPECIFICATION

#### X-Y-axes
- Linear encoder resolution better than 0.1 µm

#### P-axis
- +/- 200° AC servomotor with absolute encoder, resolution 0.0035°

#### Z-axis
- Optionally 60 mm (2.36”), AC servomotor with absolute encoder, resolution 0.5 µm

#### Positional accuracy
- <+/- 5 µm @ 3 sigma, incl. PRU/Wire/Tool/Application

#### Repeatability on the product
- <+/- 3 µm @ 3 sigma, incl. PRU/Wire/Tool/Application

#### Monitor
- 21” flat screen

#### Microscope
- Stereo zoom microscope, adjustable lighting

#### Connections
- SMEMA, USB, RJ 45, Digital I/O

#### Operating system
- Real-time, Unix®-based multi-tasking OS

#### Certification
- SEMI S2, CE

### NETWORK CONNECTIVITY

- TCP/IP/FTP data exchange
- SMEMA for in-line connections to other machines
- SEMI communication standard
- SECS/GEM

### PATTERN RECOGNITION

#### Pattern recognition unit
- Cognex® 8000 Pat Max® System

#### Recognition time
- Up to 2 ms per pattern recognition

#### Alignment correction
- Flexsearch, single point recognition incl. phase angle, two point recognition, phase angle correction +/- 5 %

#### Camera
- Moving CCD-camera, 640 x 480 pixel

#### Resolution
- 2-30 µm per pixel, adjustable using different optics

#### Image size
- Standard 1.2 mm x 1 mm bis 20 mm x 18 mm

### MANUAL WORKSTATIONS

- 4” x 4”, 6” x 6”, 8” x 6”, 10” x 6”, up to 45” x 30”
- Vacuum and / or mechanical clamping
- Heated or unheated

### AUTOMATIC PARTS HANDLING

#### Pin indexer
- Leadframes, e. g. QFN, D-PAK, PDFN and other packages

#### Belt indexer
- Flat substrates, e. g. ceramic substrates, PCB or workpiece carriers

- Leadframe length 152-324 mm, optionally < 152 mm
- Variable product length, up to 1,133 mm without index steps

- Leadframe width 18-105 mm
- Product width up to 760 mm

- Downset 3 mm
- Parts handling height up to 15 mm

- Repeatability +/- 15 µm @ 3 sigma, linear motor accuracy 3 µm
- Can be combined with manual work station, optionally heated with 2 pre-heat stations

### MAGAZINE LIFT SYSTEM

#### F & K leadframe lifts, dual axes

<table>
<thead>
<tr>
<th>Magazine width</th>
<th>Height</th>
<th>Length</th>
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</thead>
<tbody>
<tr>
<td>24-115 mm</td>
<td>94-200 mm</td>
<td>154-244 mm, optionally 234-324 mm</td>
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</tbody>
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#### F & K Substrate / boat lifts, single axis

<table>
<thead>
<tr>
<th>Magazine width</th>
<th>Height</th>
<th>Length</th>
</tr>
</thead>
<tbody>
<tr>
<td>max. 240 mm</td>
<td>max. 300 mm</td>
<td>max. 240 mm</td>
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<table>
<thead>
<tr>
<th>Substrate width</th>
<th>Substrate length &lt; 150 mm or &gt; 300 mm, Substrate widths &gt; 160 mm are treated individually as special requirements</th>
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<tbody>
<tr>
<td>max. 160 mm</td>
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QUALITY TOOLS

BOND PROCESS CONTROL (BPC): What exactly are the advantages of the new BPC?

- Closed-loop-system for continuous monitoring and real-time control of the bonding parameters time, ultrasonic power and bond force
- Adjustment of the ultrasonic power to surface variations in the current process

Tool inspection
- Graphical display of the expected positioning of wedge, cutter and wire guide using the pattern recognition unit
- Minimum set-up time with maximum traceability when changing wedge, cutter or wire guide

Traceability
- Link up to standard F & K or customer specific MES
- Link to an existing host
- For manual and automatic parts handling

Load cell
- Load cell and housing for fully automatic calibration of the bond weight

DRAG and BOND Panorama pattern recognition
- Innovative self-scanning-system for maximum overview
- Intuitive user interface for generation of bond programmes

Barcode & DMC-Reader
- Fully automatic part recognition, recipe and process data assignment
- Available as flexible hand-held DMC-reader or fixed-position integrated unit

Transducer
- Optimised, tuned system comprising transducer and ultrasonic generator
- Continuous in-house development for 25 years ensures constant and outstanding quality
- Measurement of every transducer using extensive test procedures properly documented by the transducer laboratory

BOND ACADEMY: your advantages?
Our support for implementing your requirements and optimising your processes:

- Competent advice
- Determining the correct transducer frequency for the application
- Rapid prototyping
- Validation of product design

- Sample bond tests and pilot series manufacture
- Training your service technicians
- Ramp-up-support

NOT JUST MACHINES. BUT BONDING SOLUTIONS.
Together with our parent company, Strama-MPS, we integrate our wirebonders into complete assembly lines with other joining, assembling and testing stations. Our customers profit from the combination of our bonding and automotive expertise, „One-stop-shopping”, and the interface free quality of the complete package.